



京鼎精密科技股份有限公司

2025 Third Quarter
Investor Presentation

2025/12/23

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Agenda



- Company Profile
- Financial Reports
- Business Performance and Outlook
- Q&A



Young Liu Chairman



Kevin Chiu CEO

Business

- Key components, modules, systems for semi's front-end equipment manufacturing services.
- Semi-related equipment, spares and repair services
- R&D, Sales, and Total solutions provider for semi equipment
- Medical imaging equipment manufacturing and design services.

Global Footprint



2001

Established

2015

Listed(3413 TT)

3,978 Manpower

As of 2025/11/28

NT\$ 1.085B Capital

As of 2025/9/30

NT\$ 32.55B Market Cap

As of 2025/11/28

3Q YTD 25 Revenue

NT\$15.61 B

+34.0% YoY

3Q YTD 25 GM

25.6%

-0.7 ppts YoY

3Q YTD 25 EPS

NT\$ 16.22

-8.8% YoY

Global Footprint



Manufacturing Sites: 7 Sites in 4 Regions

Rayong Production Start in 1Q25; Chonburi Pilot Run in 1Q26

Chunan #1,TW(HQ)



Chunan #2, TW



Songjiang, CN



Kunshan, CN



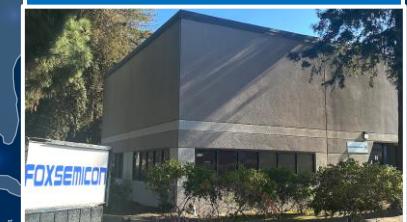
NPI (New Product Introduction)

Silicon Valley,USA



SCM & IPO

CA/TX/AZ



Kunshan
Shanghai

BKK Intl Airport

Thailand

ChonBuri

Leam Chabang Port

Rayong

U-Tapao int'l Airport
(2028 Enabled)

ChonBuri(1H26)



Rayong(1Q25)



● : MFG Center - Taiwan/China

● : MFG Center(Expansion) - Thailand

● : NPI R&D Center - USA

● : Sales / Service / IPO - Taiwan/China/USA

3Q25 Financial Reports

Statements of Comprehensive Income



(NTD in millions)	3Q25		2Q25		QoQ%	3Q24		YoY%	YTD 3Q25		YTD 3Q24		YoY%
	Revenue	Gross Profit	Revenue	Gross Profit		Revenue	Gross Profit		Revenue	Gross Profit	Revenue	Gross Profit	
Revenues	5,542	100.0%	5,203	100.0%	6.5%	4,612	100.0%	20.2%	15,614	100.0%	11,655	100.0%	34.0%
Gross Profit	1,304	23.5%	1,358	26.1%	-2.6 ppts	1,234	26.8%	-3.3 ppts	3,992	25.6%	3,061	26.3%	-0.7 ppts
Operating expenses	(568)	(10.2%)	(481)	(9.2%)		(424)	(9.1%)		(1,502)	(9.6%)	(1,163)	(10.0%)	
Operating Income	736	13.3%	877	16.9%	-3.6 ppts	810	17.7%	-4.4 ppts	2,490	16.0%	1,898	16.3%	-0.3 ppts
Non-Operating Items	152	2.7%	(456)	(8.8%)		(102)	(2.2%)		(220)	(1.4%)	302	2.6%	
Income Before Tax	888	16.0%	421	8.1%	+7.9 ppts	708	15.5%	+0.5 ppts	2,270	14.6%	2,200	18.9%	-4.3 ppts
Net Income	699	12.6%	391	7.5%	+5.1 ppts	582	12.6%	-	1,813	11.6%	1,824	15.6%	-4.0 ppts
Attributable to:													
Owners of the parent	667		369		81.0%	582		14.6%	1,760		1,824		-3.5%
Basic EPS(NTS)	6.10		3.41		2.69	5.52		0.58	16.22		17.79		(1.57)
Weighted-average outstanding shares(M)	109.35		108.17			105.42			108.48		102.48		

Balance Sheets & Key Indices



(NTD in millions)	3Q25		2Q25		3Q24	
Cash, Current financial assets	6,600	25%	7,543	29%	9,613	45%
Accounts Receivable	2,113	8%	1,815	7%	1,703	8%
Inventory	4,151	16%	3,904	15%	3,449	16%
Long-term Investments	343	1%	438	2%	440	2%
Property, plant and equipment	9,287	35%	8,016	31%	5,012	24%
Intangible assets	2,423	9%	2,425	9%	15	1%
Total Assets	26,732	100%	26,062	100%	21,506	100%
Accounts Payable	1,669	6%	1,359	5%	1,533	7%
Bank borrowings	3,264	12%	2,829	11%	1,782	8%
Bonds Payable	95	0%	222	1%	586	3%
Current Liabilities	7,137	27%	7,311	28%	4,622	21%
Total Liabilities	9,493	36%	10,077	39%	7,333	34%
Total Shareholders' Equity	17,239	64%	15,985	61%	14,173	66%
Key Indices						
AR Turnover Days		33		32		29
Days Sales of Inventory		98		99		100
AP Turnover days		40		38		39
Cash Cycle		91		93		90
Current Ratio(X)		1.89		1.88		3.26

Cash Flows



(NTD in millions)	YTD 3Q25	YTD 3Q24
Beginning Balance	7,527	6,956
Cash from operating activities	1,062	1,179
Capital expenditures	(2,618)	(1,451)
Cash dividends	(1,592)	(1,173)
Time deposits	747	720
Net Change in Debt	1,326	111
Net cash payments for business combination	(1,263)	0
Investments and others	(71)	319
Ending Balance	5,118	6,661
Free Cash Flow*	(1,556)	(272)

*Free Cash Flow=Cash from operating activities-Capital expenditures

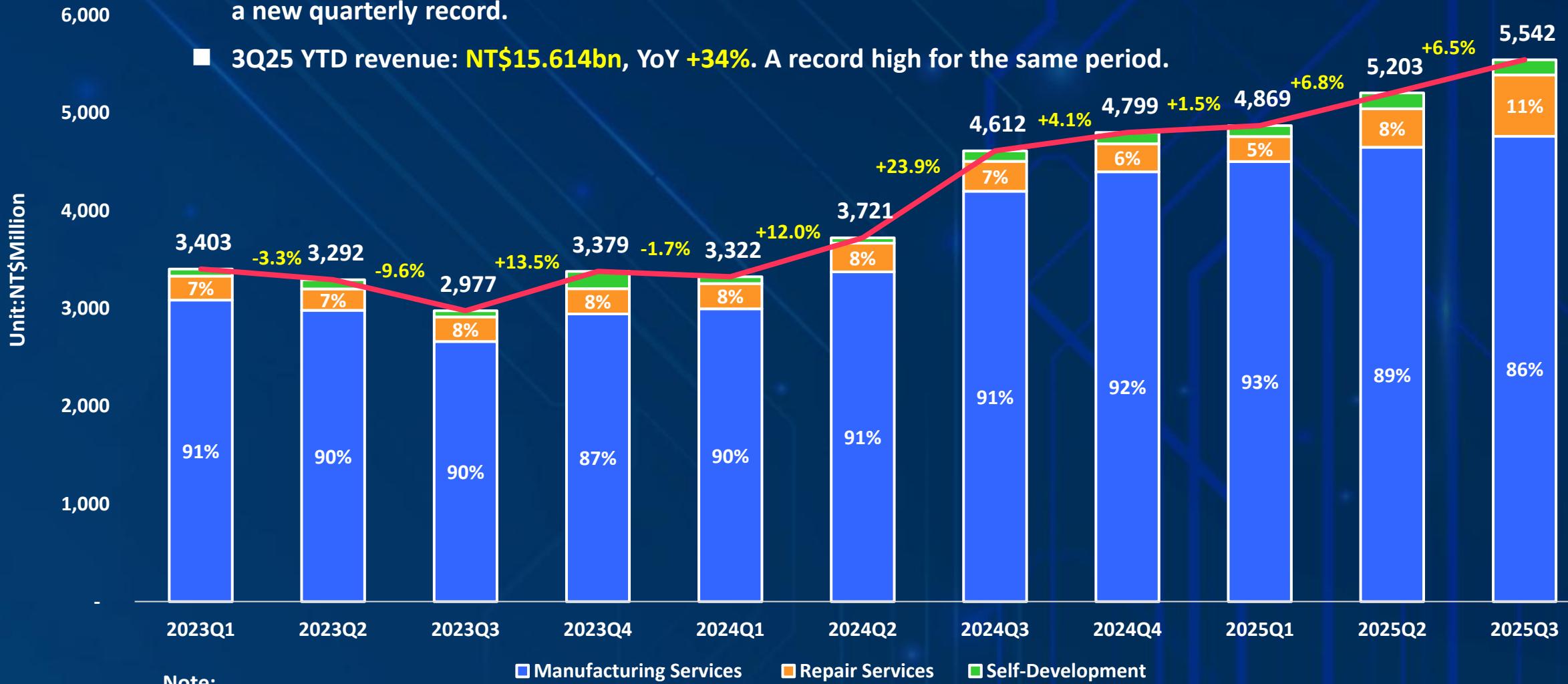
Business Performance and Outlook



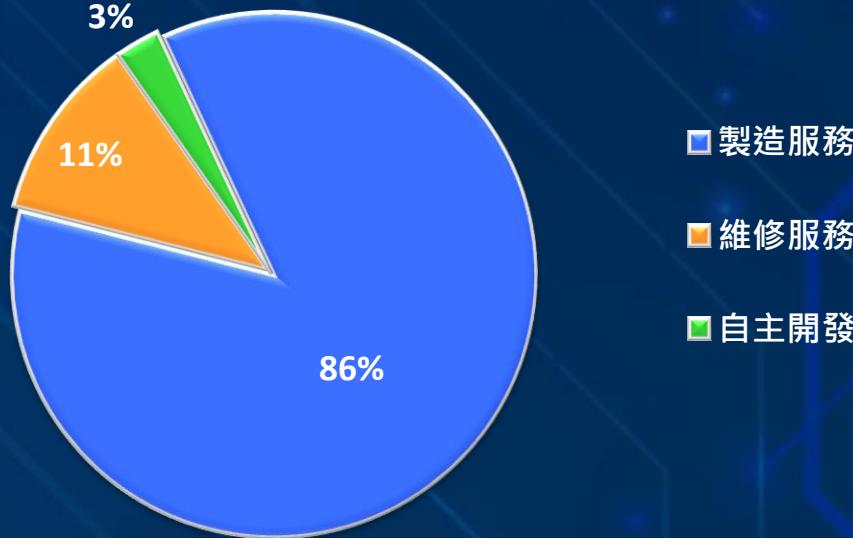
Consolidated Revenue Trend



- 3Q25 revenue: NT\$5.542bn, YoY +20.2%, QoQ +6.5%. Sixth consecutive quarter of growth, a new quarterly record.
- 3Q25 YTD revenue: NT\$15.614bn, YoY +34%. A record high for the same period.



3Q25 Revenues by Business

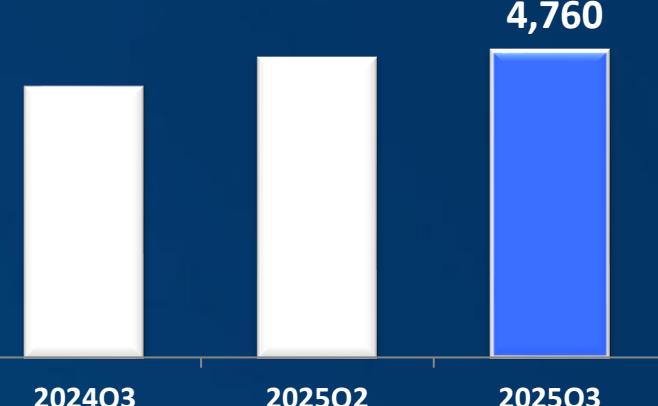


Manufacturing Services

+2.4% QoQ

+13.4% YoY

Unit: NT\$M

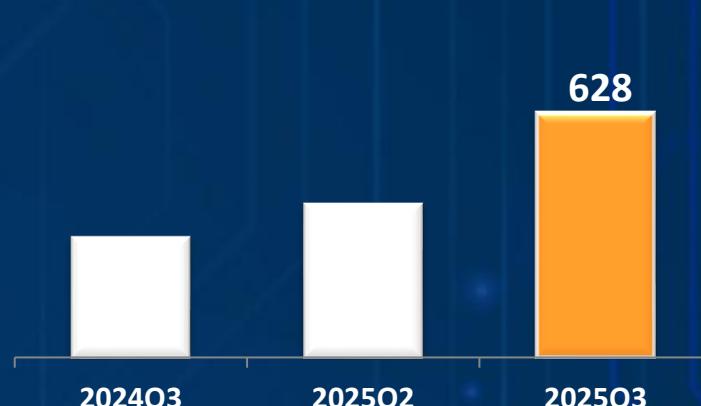


Repair Services

+60.0% QoQ

+104.5% YoY

Unit: NT\$M

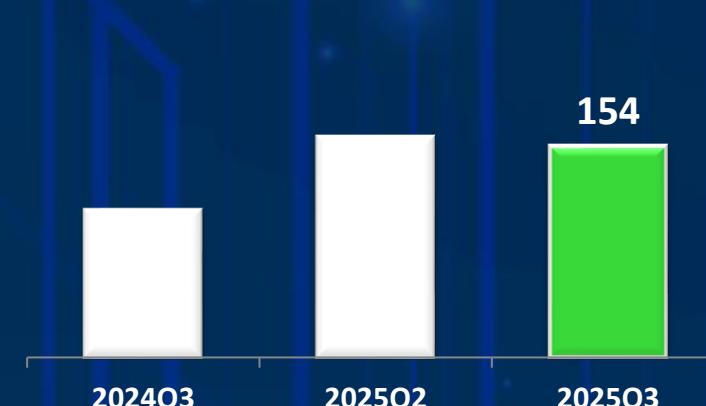


Self-Development

-4.3% QoQ

+43.2% YoY

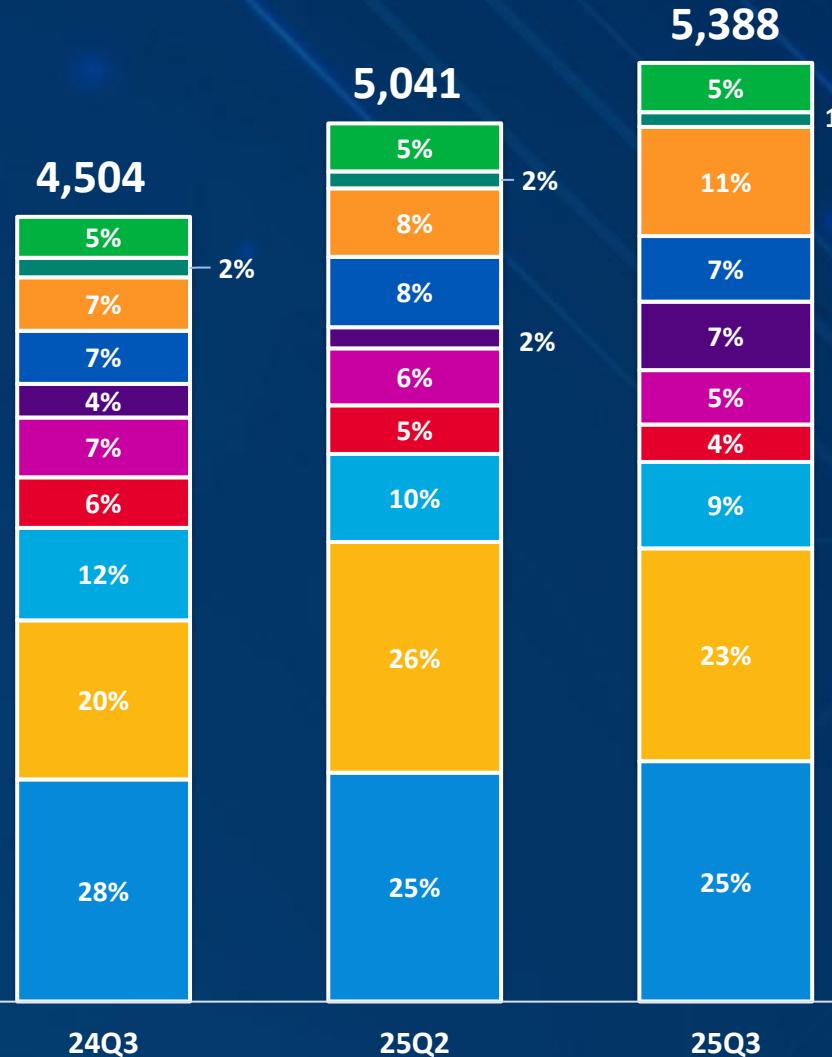
Unit: NT\$M



3Q25 Manufacturing & Repair Services by Product



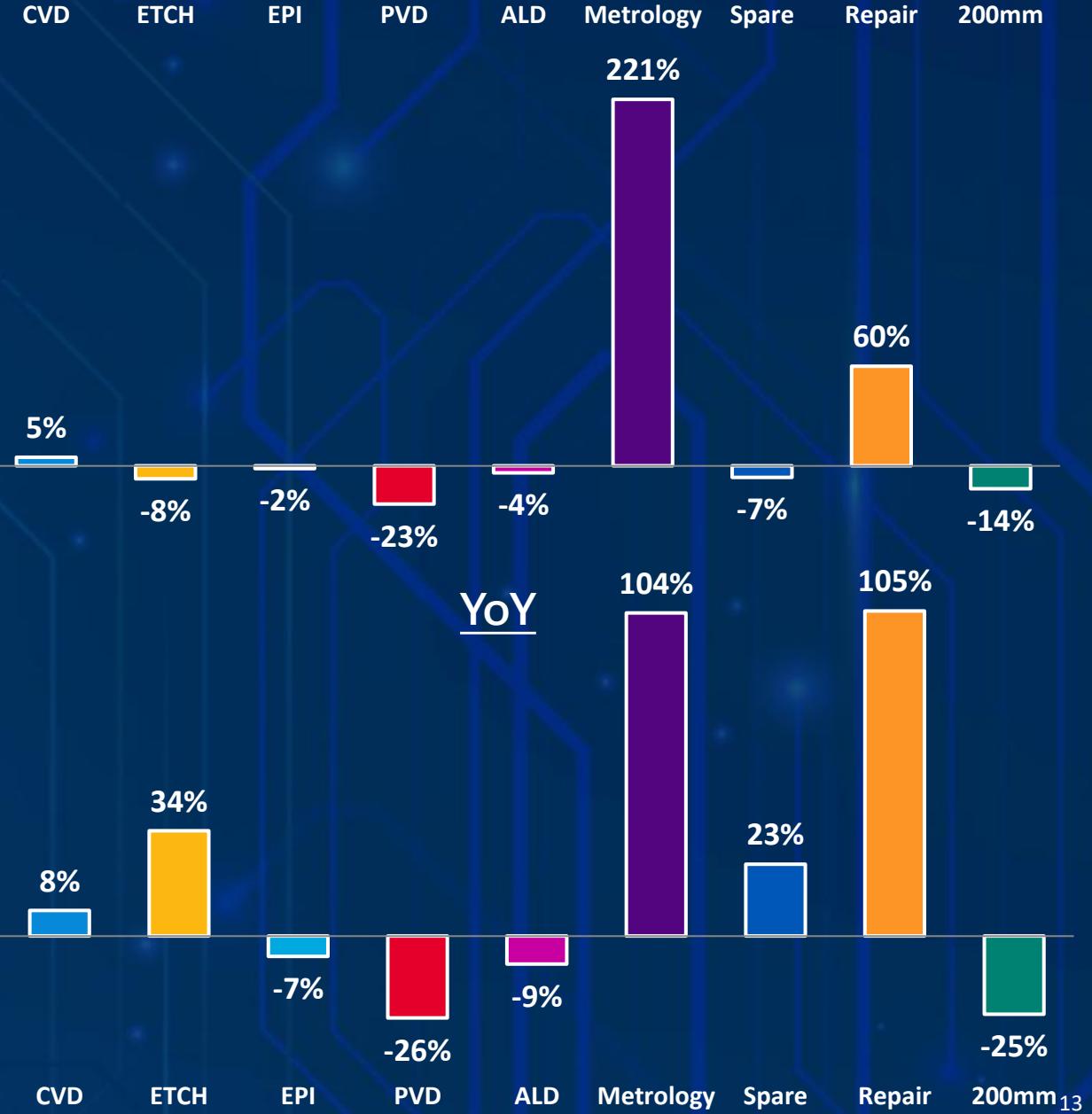
Unit:NT\$Million



FOXSEMICON INTEGRATED TECHNOLOGY INC.

CVD ETCH EPI PVD ALD Metrology Spare Repair 200mm

QoQ



YoY

CVD ETCH EPI PVD ALD Metrology Spare Repair 200mm

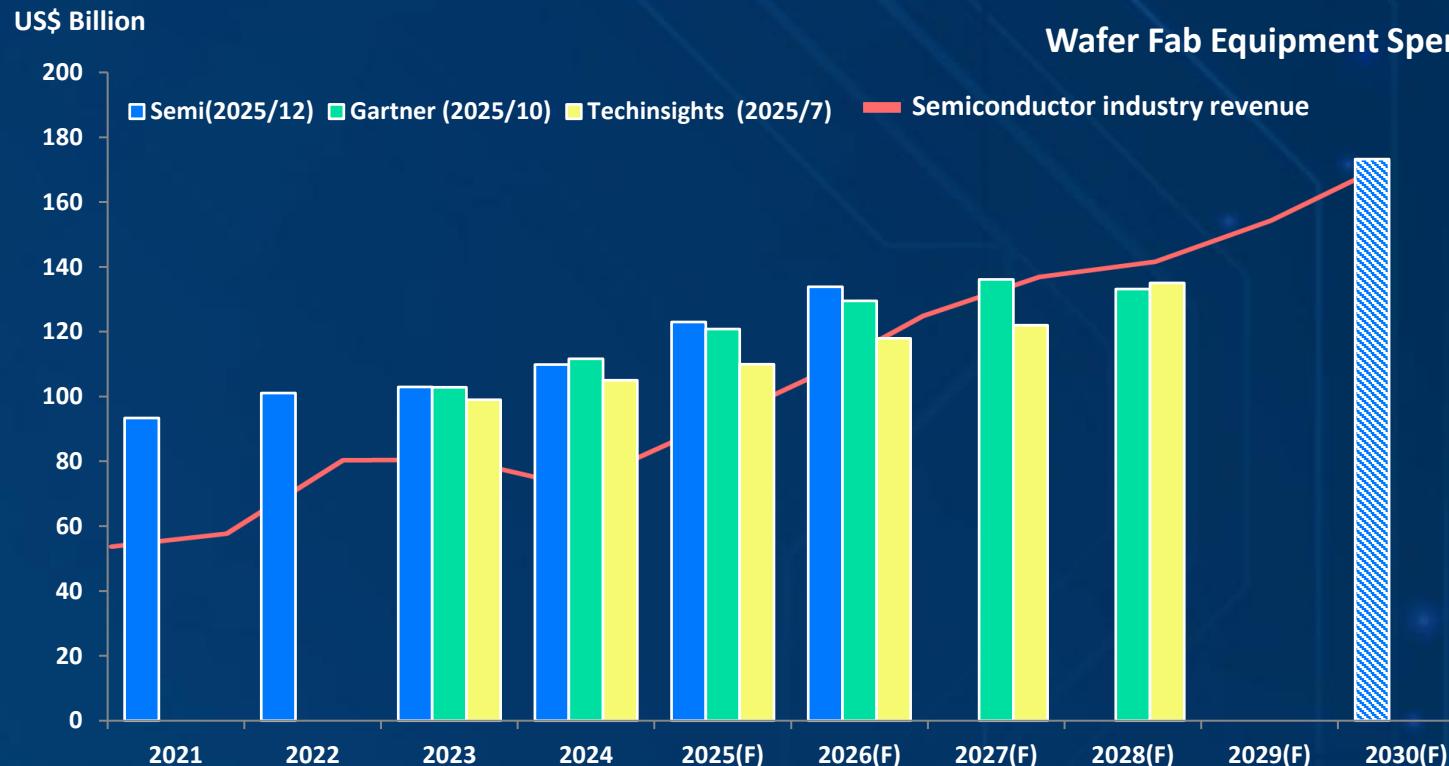
-25%

13

WFE Market



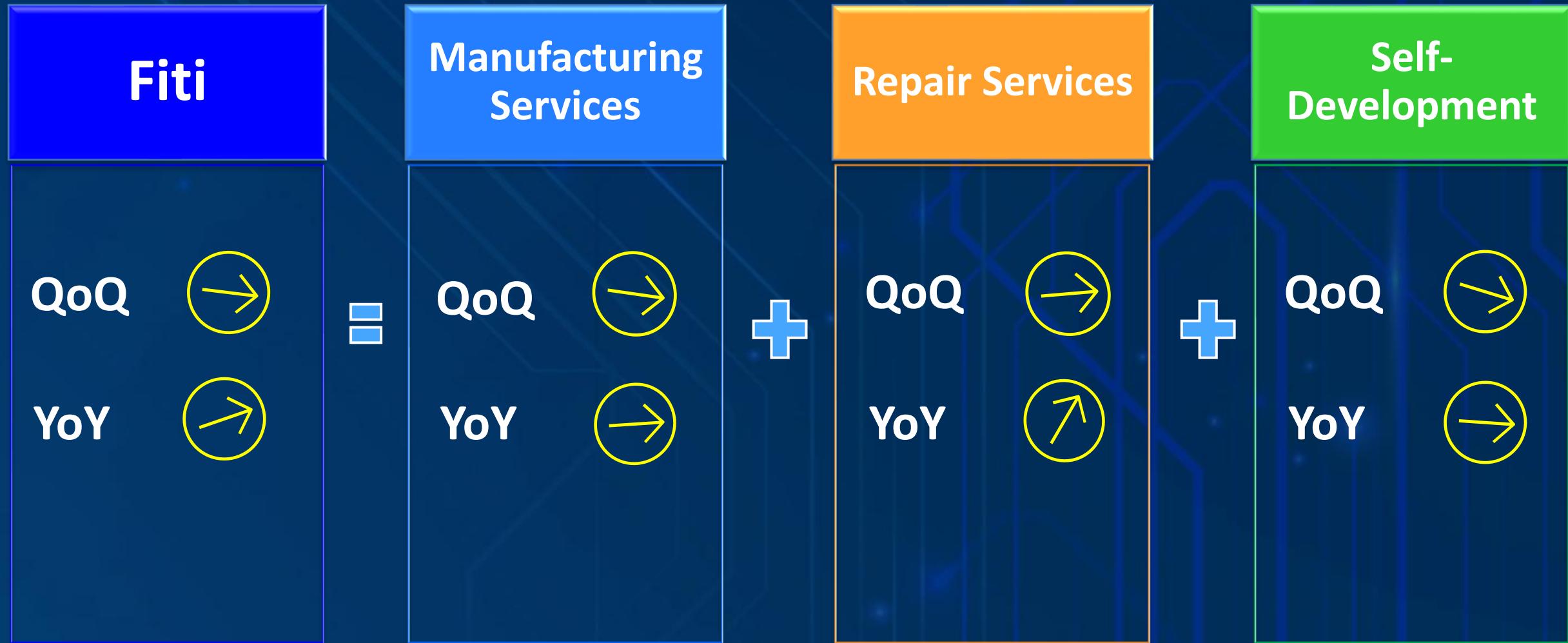
- The WFE market is projected to grow by 5%–12% in 2025, benefiting from strong demand for advanced process technologies driven by AI and HPC applications, while slower momentum in the China market and weaker demand from consumer electronics, industrial, and automotive applications partially offset growth.
- The WFE market is projected to grow by 7%–9% in 2026, benefiting from advanced process upgrades (GAA and HBM) and capacity expansion in advanced packaging. Equipment installation schedules are expected to be concentrated in the second half of the year, with market momentum expected to strengthen in 2H26 and further expand into 2027.
- Over the longer term, semiconductor equipment demand is expected to enter structural growth, benefiting from the continued expansion of AI applications, ongoing advanced process upgrades, and the acceleration of global supply chain regionalization.



WFE(\$B)	2024	2025(F)	2026(F)	2027(F)	2028(F)
Semi (2025/12)	110	123	134		
YoY	7%	12%	9%		
Gartner (2025/10)	112	121	130	136	133
YoY	9%	8%	7%	5%	-2%
TechInsights (2025/7)	105	110	118	122	135
YoY	6%	5%	7%	3%	11%

Source: Semi/Gartner/TechInsights

4Q25 Business Outlook



Awards & Honors



Onto Innovation
Supplier Excellence Award



TCSA
Taiwan Corporate Sustainability Report
Silver Award

Chonburi New Plant Commences Operations

Chonburi plant commenced operations on Nov. 11, with pilot production scheduled for 1Q26.



■ Operation Highlights

- 3Q revenue reached a new quarterly high, while revenue for the first three quarters also set a new record for the same period; however, profitability for the first three quarters was impacted by foreign exchange losses incurred in 2Q.
- The Chonburi plant commenced operations in November and is scheduled to enter pilot production in 1Q26. The Company's overseas manufacturing footprint continues to be strengthened, enhancing the resilience and flexibility of its global supply chain.
- The Company's performance in customer collaboration and sustainability governance continues to receive recognition from international customers and external institutions.

■ Outlook & Growth Strategy

- The near-term demand slowdown from 4Q25 through the first half of 2026 primarily reflects customers' earlier inventory preparation and adjustments to equipment installation schedules, while customer order placement remains relatively cautious.
- As capacity expansion in advanced process technologies and high-end memory ramps up in the second half of 2026, equipment investment momentum is expected to recover, supporting a rebound in the Company's revenue in the second half of the year, with overall revenue performance in 2026 remaining stable.
- Near-term gross margin pressure, with revenue scale expansion and operating efficiency improvements providing support to profitability.
- The expansion of AI and HPC applications is driving capacity expansion in advanced logic, high-end memory, and advanced packaging. As process layers increase and complexity rises, demand for key equipment, including etch, deposition, and metrology, is rising, and semiconductor equipment demand is entering a phase of structural growth.

Q&A



Thank you